

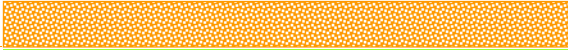
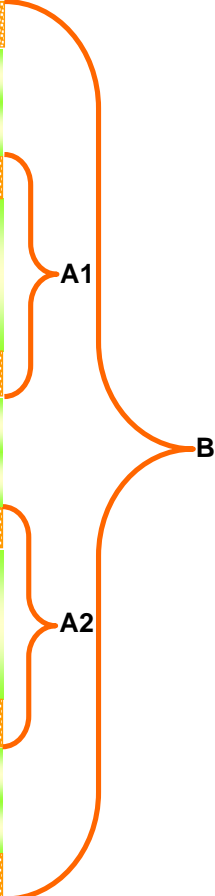








**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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06 237 FR4 35 L71.70 P10

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

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Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	35 $\mu$	Copper		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
Layer-2	70 $\mu$	Copper		
	710 $\mu$	L-FR4		
Layer-3	70 $\mu$	Copper		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
Layer-4	70 $\mu$	Copper		
	710 $\mu$	L-FR4		
Layer-5	70 $\mu$	Copper		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
Layer-99	35 $\mu$	Copper		

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